The differential inputs A+, A- are swapped and connected to ADS8354 AINM_A and AINP_A. The differential inputs B+, B- are swapped and connected to ADS8354 AINM_B and AINP_B. Since both signals are sampled simultaneously there's no impact. Adjust in software by inverting and swapping the results.

This was done to optimize layout for best performance minimizing vias and signal crossings.

NOTE

The differential inputs A+, A- are swapped and connected to ADS8354 AINM_A and AINP_A. The differential inputs B+, B- are swapped and connected to ADS8354 AINM_B and AINP_B. Since both signals are sampled simultaneously there's no impact. Adjust in software by inverting and swapping the results.

This was done to optimize layout for best performance minimizing vias and signal crossings.
- Disable with adding a jumper at J7 pins 4-3
- Enable with adding a jumper at J7 pins 4-6
- Control w/ host through J7 pin 4

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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